


Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STM32F051R6T7TR	G55W*440XXB	A	9988	2017-07-11
	Amount	UoM	Unit type	ST ECOPACK Grade
	389.00	mg	Each	ECOPACK® 2
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFP	10x10x1.4	64	L Bend	
Comment	Package : 5W LQFP 64 10x10x1.4 1 0051434			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-12th January 2017				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	G55W*440XXB				5000001.0	999994.0
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or dies	M-011 Other inorganic materials	20.573	mg	supplier	die	Silicon (Si)	7440-21-3		19.821	mg	963447	50954
				supplier	metallization	Aluminium (Al)	7429-90-5		0.051	mg	2479	131
				supplier	metallization	Copper (Cu)	7440-50-8		0.255	mg	12395	656
				supplier	metallization	Cobalt (Co)	7440-48-4		0.048	mg	2333	123
				supplier	metallization	Titanium (Ti)	7440-32-6		0.014	mg	681	36
				supplier	metallization	Tungsten (W)	7440-33-7		0.028	mg	1361	72
				supplier	Passivation	Silicon Nitride	12033-89-5		0.033	mg	1604	85
				supplier	Passivation	Silicon Oxide	7631-86-9		0.323	mg	15700	830
				Supplier	Mold compound	Epoxy Resin	Proprietary		18.202	mg	76404	46792
Encapsulation	M-011 Other inorganic materials	238.235	mg	Supplier	Mold compound	Phenol Resin	Proprietary		12.135	mg	50937	31195
				Supplier	Mold compound	Carbon Black	1333-86-4		0.728	mg	3056	1871
				Supplier	Mold compound	Silica Fused	60676-86-0		207.170	mg	869603	532570
				Supplier	Wire	Gold	7440-57-5		0.670	mg	1000000	1722
Bondig wire	M-011 Other inorganic materials	0.670	mg	Supplier	Wire	Gold	7440-57-5		0.670	mg	1000000	1722
Finishing	M-011 Other inorganic materials	1.439	mg	Supplier	Connection coating	Tin	7440-31-5		1.439	mg	1000000	3699
				Supplier	Alloy	Copper	7440-50-8		121.887	mg	951632	313334
Leadframe	M-011 Other inorganic materials	128.082	mg	Supplier	Alloy	Iron	12597-68-1		2.939	mg	22946	7555
				JIG-R	Alloy	Lead	7439-92-1		0.000	mg	1	0
				Supplier	Alloy	Phosphorus	7723-14-0		0.032	mg	250	82
				Supplier	Alloy	Zinc	7440-66-6		0.162	mg	1265	416
				Supplier	Alloy	Silver	7440-22-4		3.062	mg	23907	7871